



Material Content Data Sheet



Sales Product Name		TLE4678-2LD		Issued		20. July 2018		
MA#		MA001238828						
Package		PG-TSON-10-2		Weight*		31.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.689	2.18	2.18	21778	21778
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		105	
	non noble metal	zinc	7440-66-6	0.013	0.04		419	
	non noble metal	iron	7439-89-6	0.265	0.84		8382	
wire	non noble metal	copper	7440-50-8	10.773	34.04	34.93	340358	349264
	non noble metal	copper	7440-50-8	0.056	0.18	0.18	1763	1763
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.12		1206
plastics	plastics	epoxy resin	-	1.966	6.21		62130	
	inorganic material	silicondioxide	60676-86-0	17.087	53.98	60.31	539865	603201
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11693	11693
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2030	2030
glue	plastics	epoxy resin	-	0.081	0.26		2568	
	noble metal	silver	7440-22-4	0.244	0.77	1.03	7703	10271
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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